

# **TM40N02D**

## **N-Channel Enhancement Mosfet**

### **General Description**

- Low R<sub>DS(ON)</sub>
- RoHS and Halogen-Free Compliant

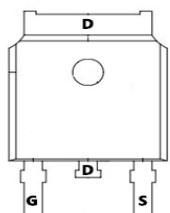
### **Applications**

- Load switch
- PWM

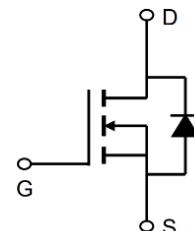
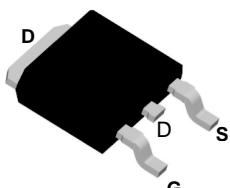
### **General Features**

V<sub>DS</sub> = 20V I<sub>D</sub> = 40A  
R<sub>DS(ON)</sub> = 7.5mΩ(typ.) @ V<sub>GS</sub> = 4.5V

100% UIS Tested  
100% R<sub>g</sub> Tested



**D:TO-252-3L**



Marking: 40N02

### **Absolute Maximum Ratings (T<sub>A</sub> = 25°C Unless Otherwise Noted)**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	20	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	40	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	78	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	23	mJ
I <sub>AS</sub>	Avalanche Current	21	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	15	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### **Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	7.5	°C/W

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**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=\pm 12\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	0.5	0.7	1.2	V
$R_{\text{DS}(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{\text{GS}}=4.5\text{V}$ , $I_D=15\text{A}$	-	7.5	11	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=10\text{A}$	-	11	17.5	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	860	-	pF
$C_{\text{oss}}$	Output Capacitance		-	182	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	164	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}$ , $I_D=15\text{A}$ , $V_{\text{GS}}=4.5\text{V}$	-	15	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	2	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	5.2	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=10\text{V}$ , $I_D=15\text{A}$ , $R_{\text{GEN}}=3\Omega$ , $V_{\text{GS}}=4.5\text{V}$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	25	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	37	-	ns
$t_f$	Turn-off Fall Time		-	14	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	120	A
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=30\text{A}$	-	-	1.2	V

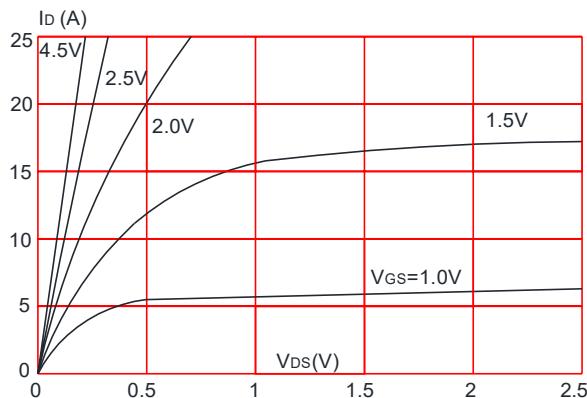
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

 2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=10\text{V}$ ,  $V_G=4.5\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{\text{AS}}=9.6\text{A}$ 

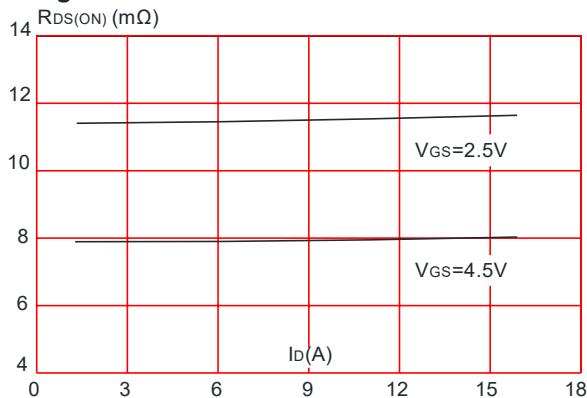
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

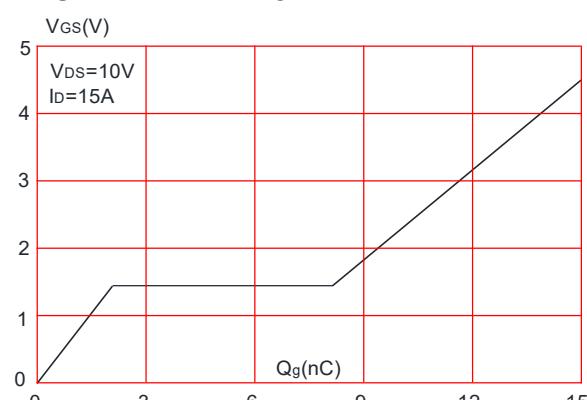
**Figure 1:** Output Characteristics



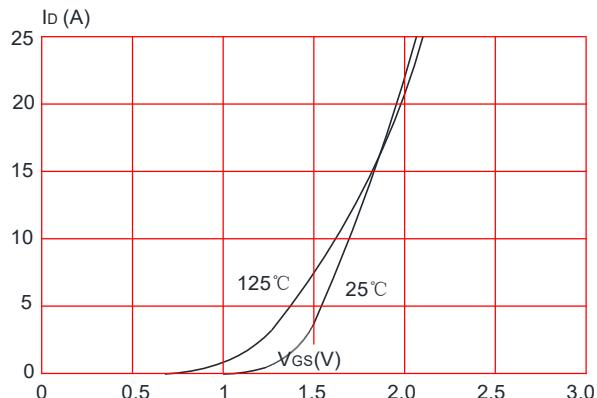
**Figure 3:** On-resistance vs. Drain Current



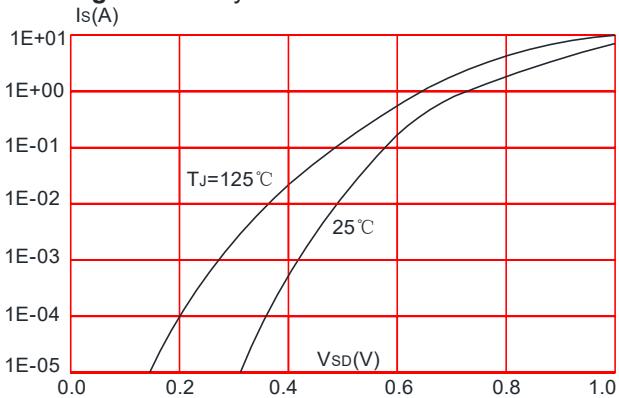
**Figure 5:** Gate Charge Characteristics



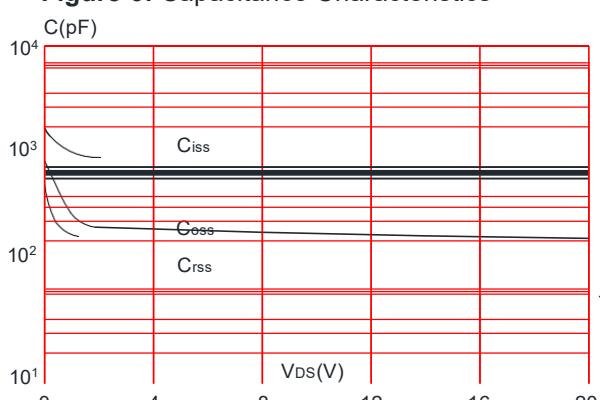
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics



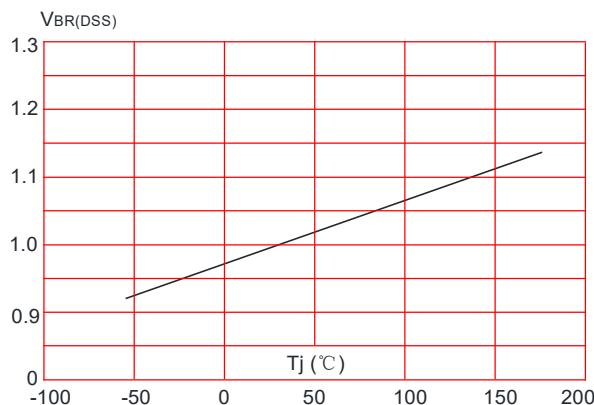
**Figure 6:** Capacitance Characteristics



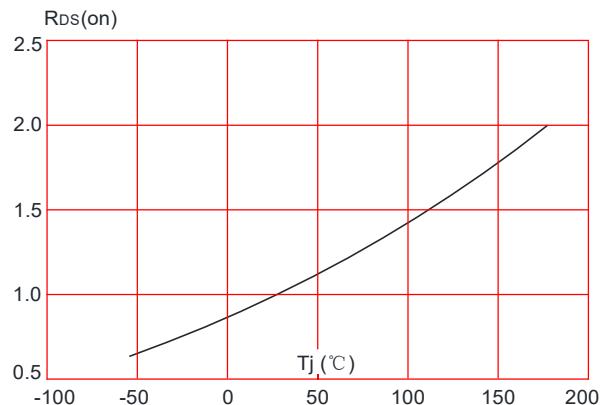
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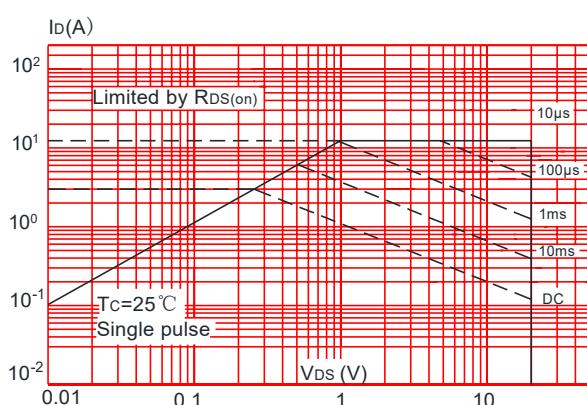
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



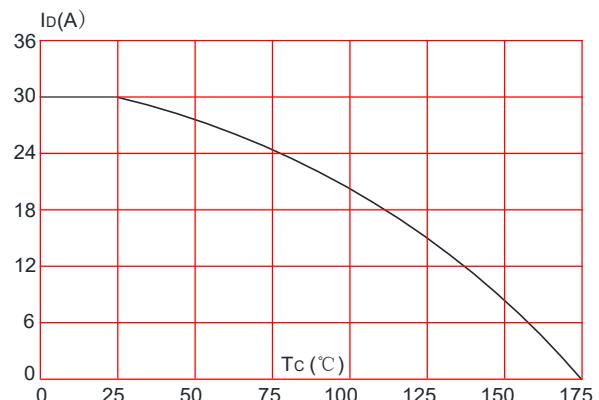
**Figure 8:** Normalized on Resistance vs. Junction Temperature



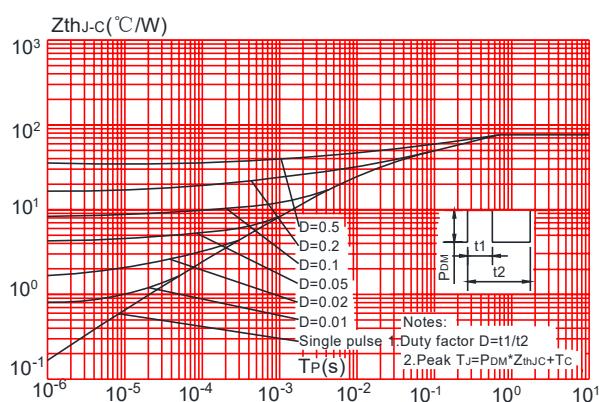
**Figure 9:** Maximum Safe Operating Area



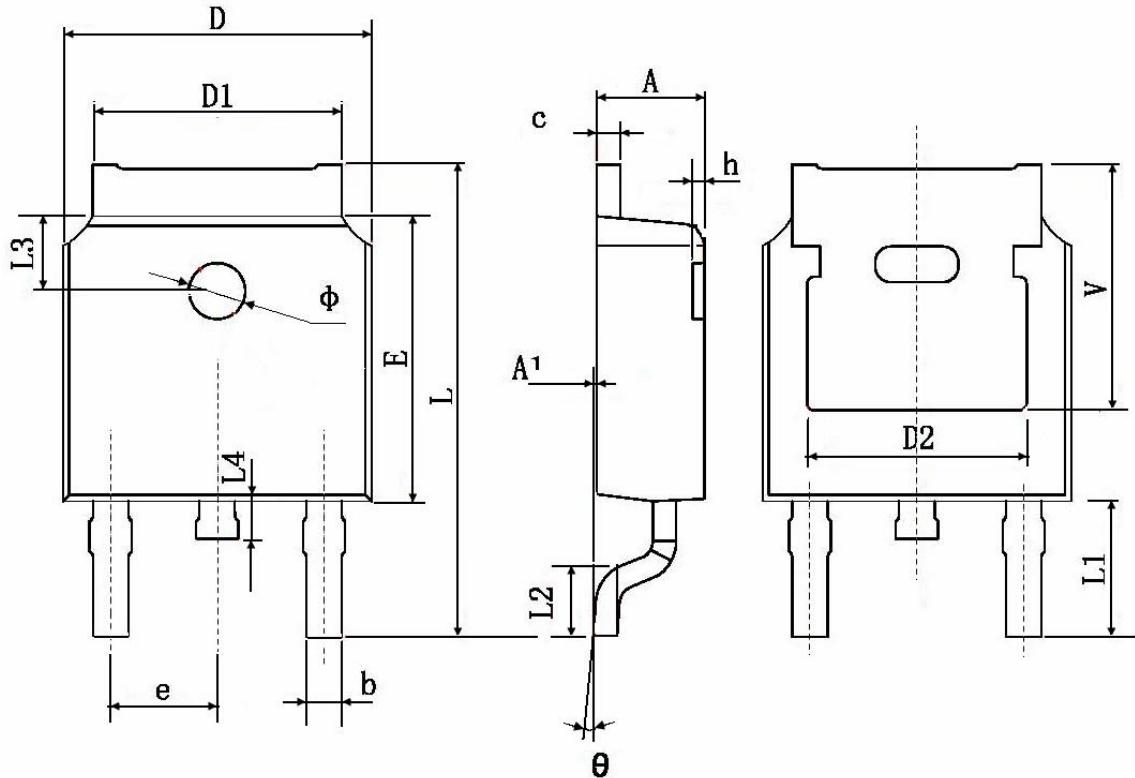
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case



## Package Information: TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	